

What's New - September 2020

Article

Business agility for the new, smarter normal



Data centers must be agile to handle today's rapidly changing and uncertain business conditions. With Lenovo you can modernize your data center with the largest breadth of agile preconfigured hybrid cloud solutions so you, the Data-Centered, can harness the flexibility and scalability of the cloud.

This month, Lenovo launched updates to its software-defined infrastructure solutions:

- **ThinkAgile HX**, now with AMD EPYC processors
- **ThinkAgile MX Azure Stack HCI** Edge and Server Appliances
- **ThinkAgile VX** with VMware vSAN
- **Kubernetes** infrastructure offering with a new offering from our partner **Diamanti**
- **ThinkSystem DE and DM storage** with solutions that include our partners such as **Veeam**
- **Lenovo Professional Services**: Automate and optimize your hybrid cloud solution with Lenovo cloud experts

Learn about these new offerings on our [Agile Solutions landing page](#).

New options for SR645 and SR665

This month, we announced new option support for SR645 and SR665, our 2-socket AMD EPYC processor-based servers.

New support includes:

- New support for single-socket (P-suffix) processors
- New support for Intel P4510, P4610, S4510 and S4610 SSD drive families
- New support for additional OCP 3.0 network adapters
- New support for additional PCIe network adapters



In addition:

- The SR645 now supports 12x NVMe drives
- The SR665 now supports 7mm drives installed in the slot 3 area in riser 1

Details in the product guides

- [ThinkSystem SR645 product guide](#)
- [ThinkSystem SR665 product guide](#)

New storage options for ThinkSystem servers

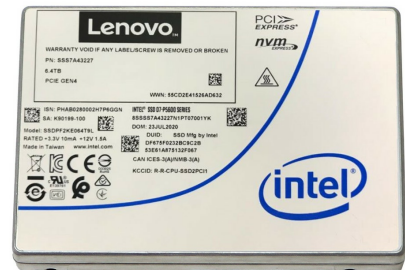
This month Lenovo announced a wide variety of new SSDs, flash storage adapters, and high-capacity HDDs for use in ThinkSystem servers.

New SSD drive options just announced. Compare these drives in our SSD comparison tool:

[Lenovo ThinkSystem SSD Portfolio](#)

New drives are as follows:

- New [Intel P5500](#) NVMe drives
 - ThinkSystem U.2 Intel P5500 1.92TB Entry NVMe PCIe 4.0 x4 Hot Swap SSD, 4XB7A17145
 - ThinkSystem U.2 Intel P5500 3.84TB Entry NVMe PCIe 4.0 x4 Hot Swap SSD, 4XB7A17146
 - ThinkSystem U.2 Intel P5500 7.68TB Entry NVMe PCIe 4.0 x4 Hot Swap SSD, 4XB7A17147
- New [Intel P5600](#) NVMe drives
 - ThinkSystem U.2 Intel P5600 1.6TB Mainstream NVMe PCIe 4.0 x4 Hot Swap SSD, 4XB7A17152
 - ThinkSystem U.2 Intel P5600 3.2TB Mainstream NVMe PCIe 4.0 x4 Hot Swap SSD, 4XB7A17153
 - ThinkSystem U.2 Intel P5600 6.4TB Mainstream NVMe PCIe 4.0 x4 Hot Swap SSD, 4XB7A17154
 - ThinkSystem 3.5" Intel P5600 1.6TB Mainstream NVMe PCIe 4.0 x4 Hot Swap SSD, 4XB7A17155
 - ThinkSystem 3.5" Intel P5600 3.2TB Mainstream NVMe PCIe 4.0 x4 Hot Swap SSD, 4XB7A17156
 - ThinkSystem 3.5" Intel P5600 6.4TB Mainstream NVMe PCIe 4.0 x4 Hot Swap SSD, 4XB7A17157
- New [Kioxia CM6-V](#) drives
 - ThinkSystem U.3 Kioxia CM6-V 1.6TB Mainstream NVMe PCIe 4.0 x4 Hot Swap SSD, 4XB7A17112



- ThinkSystem U.3 Kioxia CM6-V 3.2TB Mainstream NVMe PCIe4.0 x4 Hot Swap SSD, 4XB7A17113
- ThinkSystem U.3 Kioxia CM6-V 6.4TB Mainstream NVMe PCIe4.0 x4 Hot Swap SSD, 4XB7A17114
- ThinkSystem U.3 Kioxia CM6-V 800GB Mainstream NVMe PCIe 4.0 x4 Hot Swap SSD, 4XB7A64175
- ThinkSystem 3.5" Kioxia CM6-V 1.6TB Mainstream NVMe PCIe4.0 x4 Hot Swap SSD, 4XB7A17115
- ThinkSystem 3.5" Kioxia CM6-V 3.2TB Mainstream NVMe PCIe4.0 x4 Hot Swap SSD, 4XB7A17116
- ThinkSystem 3.5" Kioxia CM6-V 6.4TB Mainstream NVMe PCIe4.0 x4 Hot Swap SSD, 4XB7A17117
- ThinkSystem 3.5" Kioxia CM6-V 800GB Mainstream NVMe PCIe 4.0 x4 Hot Swap SSD, 4XB7A64176
- New [Kioxia CM6-R](#) drives
 - ThinkSystem U.3 Kioxia CM6-R 3.84TB Entry NVMe PCIe 4.0 x4 Hot Swap SSD SED, 4XB7A38269
 - ThinkSystem U.3 Kioxia CM6-R 3.84TB Entry NVMe PCIe 4.0 x4 Hot Swap SSD, 4XB7A64141
 - ThinkSystem U.3 Kioxia CM6-R 7.68TB Entry NVMe PCIe 4.0 x4 Hot Swap SSD SED, 4XB7A38270
 - ThinkSystem U.3 Kioxia CM6-R 7.68TB Entry NVMe PCIe 4.0 x4 Hot Swap SSD, 4XB7A64142
- New capacities of [Micron 5300](#) drives
 - ThinkSystem 2.5" 5300 3.84TB Mainstream SATA 6Gb Hot Swap SSD SED, 4XB7A64222
 - ThinkSystem 2.5" 5300 960GB Entry SATA 6Gb Hot Swap SSD SED, 4XB7A38141
 - ThinkSystem ST50 3.5" 5300 480GB Entry SATA 6Gb Non Hot Swap SSD, 4XB7A17205
 - ThinkSystem ST50 3.5" 5300 960GB Entry SATA 6Gb Non Hot Swap SSD, 4XB7A17206
- New capacity of [Samsung PM1643a](#) drives
 - ThinkSystem 3.5" PM1643a 7.68TB Entry SAS 12Gb Hot Swap SSD, 4XB7A17059
- New SED versions of [Samsung PM1733](#) drives
 - ThinkSystem U.2 PM1733 3.84TB Entry NVMe PCIe 4.0 x4 Hot Swap SSD SED, 4XB7A38257
 - ThinkSystem U.2 PM1733 7.68TB Entry NVMe PCIe 4.0 x4 Hot Swap SSD SED, 4XB7A38258
- New capacities of [Samsung PM1733](#) NVMe drives
 - ThinkSystem U.2 PM1733 15.36TB Entry NVMe PCIe 4.0 x4 Hot Swap SSD, 4XB7A38284
 - ThinkSystem U.2 PM1733 7.68TB Entry NVMe PCIe 4.0 x4 Hot Swap SSD, 4XB7A38283

We announced new 18TB HDD drive options (see the [ThinkSystem HDD Summary](#))

- New 18TB HDDs
 - ThinkSystem 3.5" 18TB 7.2K SAS 12Gb Hot Swap 512e HDD L1, 4XB7A38266
 - ThinkSystem 3.5" 18TB 7.2K SATA 6Gb Hot Swap 512e HDD, 4XB7A38130

We also announced a new Samsung flash storage adapter capacity:

- New capacity of [Samsung PM1735](#) flash adapter
 - ThinkSystem HHHL PM1735 6.4TB Mainstream NVMe PCIe 4.0 x8 Flash Adapter, 4XB7A14077

Updates to HPC offerings

In September, we announced the following updates to our HPC offerings:

- **NVIDIA A100 GPU:** We're offering the new NVIDIA A100 GPU on the ThinkSystem SR670 with additional servers coming later. Read about the A100 in the [ThinkSystem GPU Summary](#).
- **LeSI quarterly updates** include adding the NVIDIA A100 and Quadro RTX4000 GPU plus support for NVIDIA (formerly Mellanox) Ethernet networking switches. Details of all updates in the [LeSI product guide](#).
- **DSS-G updates** include a 16TB HDD data drive option and 800GB logtip drive option for the D3284 storage enclosure, and adding the Mellanox AS4610 as the optional Gigabit Ethernet switch for management. Details in the [DSS-G product guide](#).



Figure 1. ThinkSystem NVIDIA A100 40GB PCIe 4.0 Passive GPU

Micro Datacenter 6U Rack Cabinets

Lenovo ThinkSystem 6U Micro Datacenter rack offerings are industry-standard 19-inch server cabinets that are designed for rack servers that are to be deployed outside of traditional data centers. The rack cabinets offer a small footprint by orienting the installed servers vertically in the rack.

The 6U cabinets are available in three different depths:

- 800mm depth
- 1200mm depth
- 1200mm depth with an additional acoustic door (a total of 1490mm depth)



Figure 2. ThinkSystem Micro Datacenter 6U Acoustic 1200mm Deep Rack

Details about the new rack cabinets can be found in the [Micro Datacenter 6U Rack Cabinets product guide](#).

Related product families

Product families related to this document are the following:

- [Drives](#)
- [PCIe Flash Adapters](#)
- [ThinkAgile HX Series for Nutanix](#)
- [ThinkAgile MX Series for Microsoft Azure Local](#)
- [ThinkAgile VX Series for VMware](#)
- [ThinkSystem SR645 Server](#)
- [ThinkSystem SR665 Server](#)

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